

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2003-031944
 (43)Date of publication of application : 31.01.2003

(51)Int.Cl. H05K 3/46

(21)Application number : 2001-219780
 (22)Date of filing : 19.07.2001

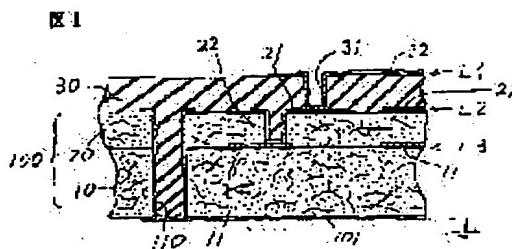
(71)Applicant : HITACHI AIC INC
 (72)Inventor : ISODA SATOSHI
 OWADA MASASHI
 OZEKI KIYOSHI
 FUKUSATO KENSHIRO
 IWASAKI YASUHIRO

(54) MULTILAYERED PRINTED WIRING BOARD AND METHOD OF MANUFACTURING LINE SIGNAL LINE THEREOF

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a multilayer printed wiring board and a method of manufacturing its line signal lines which is superior in elevating the packaging density of the wiring board and mechanical strength and manufactures them with a few steps at a low cost.

SOLUTION: The printed wiring board has a core board (100), formed by stacking a surface layer (20) on the surface of an inner board (10). At least a buildup layer (30) is formed on the surface of the core board, plating blind through-holes (22), for taking out line signal lines (11) formed on the inner board (10) surface are formed into the surface layer (20) of the core board, blind plating through-holes (31) for taking out line signal lines (21), formed on the surface of a surface layer of a core board (1100) are formed into the buildup layer (30), and only one buildup layer is stacked on the surface of the core board to form transmission lines L1-L3 of the three-layer structure.



LEGAL STATUS

[Date of request for examination] 21.01.2004

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]